

ON Semiconductor®

FDD4243-F085

P-Channel PowerTrench $^{\circledR}$ MOSFET -40V, -14A, 64m Ω

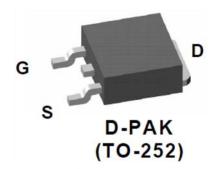
Features

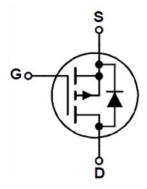
- Typ $r_{DS(on)}$ = 36m Ω at V_{GS} = -10V, I_D = -6.7A
- Typ $r_{DS(on)}$ = 48m Ω at V_{GS} = -4.5V, I_D = -5.5A
- Typ $Q_{q(TOT)}$ = 21nC at V_{GS} = -10V
- \blacksquare High performance trench technology for extremely low $r_{\mathsf{DS}(\mathsf{on})}$
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Inverter
- Power Supplies







MOSFET Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain to Source Voltage		-40	V
V_{GS}	Gate to Source Voltage		±20	V
	Drain Current Continuous (T _C < 130°C, V _{GS} = 10V)		-14	۸
I _D	Pulsed		See Figure 4	_ A
E _{AS}	Single Pulse Avalanche Energe	(Note 1)	84	mJ
D	Power Dissipation		50	W
P_{D}	Dreate above 25°C		0.34	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to +175	οС

Thermal Characteristics

$R_{\theta JC}$	Maximum Thermal Resistance Junction to Case	3	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance Junction to Ambient TO-252, 1in ² copper pad area	40	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD4243	FDD4243-F085	TO252	13"	12mm	2500 units

Electrical Characteristics T_J = 25°C unless otherwise noted

Parameter

Off Cha	racteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-40	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	ID = -250μA, referenced to 25°C	-	-32	-	mV/°C
1	Zero Gate Voltage Drain Current	V _{DS} = -32V	-	-	-1	μА
IDSS	Zero Gate Voltage Brain Gurrent	$T_{J} = 125^{\circ}C$	-	-	-100	μΛ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$	-	-	±100	nA

Test Conditions

Min

Тур

Max

Units

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-1.4	-1.6	-3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	ID = -250μ A, referenced to 25° C	-	4.7	-	mV/°C
		$I_D = -6.7A, V_{GS} = -10V$	-	36	44	
roce	Drain to Source On Resistance	$I_D = -5.5A, V_{GS} = -4.5V$	-	48	64	mΩ
	$I_D = -6.7A, V_{GS} = -10V,$ $T_J = 150^{\circ}C$	-	57	70	11152	
g _{FS}	Forward Transconductance	$I_D = -6.7A, V_{DS} = -5V,$	-	23	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	.,	-	1165	1550	pF
Coss	Output Capacitance	$V_{DS} = -20V, V_{GS} = 0V,$ f = 1MHz	-	165	220	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1101112	-	90	135	pF
R_G	Gate Resistance	f = 1MHz	-	4	-	Ω
$Q_{g(TOT)}$	Total Gate Charge		-	21	29	nC
Q _{gs}	Gate to Source Gate Charge	V _{DD} = -20V, V _{GS} = -10V	-	3.4	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	I _D = -6.7A	-	4	-	nC

Note:

1. A suffix as "...F085P" has been temporarily introduced in order to manage a double source strategy as ON Semiconductor has officially announced in Aug 2014.

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		-	6	12	ns
t _r	Rise Time	V _{DD} = -20V, I _D = -6.7A	-	15	26	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = -10V, R_{GEN} = 6Ω	-	22	35	ns
t _f	Fall Time		1	7	14	ns

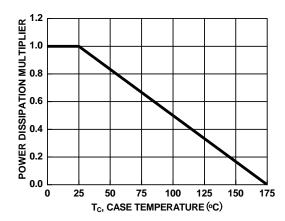
Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Voltage	I_{SD} = -6.7A, V_{GS} =0V	-	-0.86	-1.2	V
t _{rr}	Reverse Recovery Time	L = 6.7A dL /dt = 100A/vo	-	29	43	ns
Q _{rr}	Reverse Recovery Charge	$I_{SD} = -6.7A$, $dI_{SD}/dt = 100A/\mu s$	-	30	44	nC

2. Starting $T_J = 25^{\circ}C$, L = 3mH, $I_{AS} = 7.5A$, $V_{GS} = 10V$, $V_{DD} = 40V$ during the inductor charging time and 0V during the time in avalanche.

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/ All ON Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.





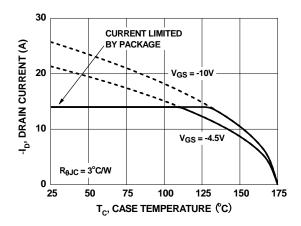
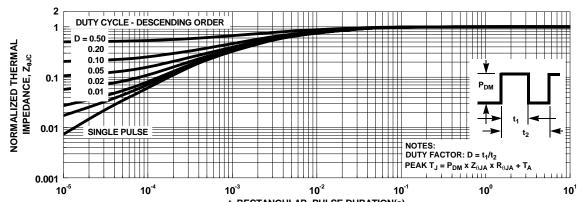


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature



t, RECTANGULAR PULSE DURATION(s)
Figure 3. Normalized Maximum Transient Thermal Impedance

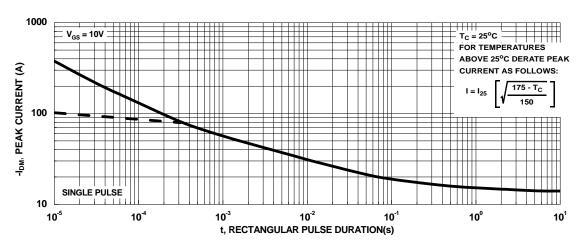


Figure 4. Peak Current Capability

Typical Characteristics

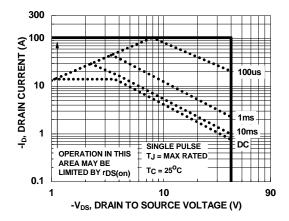
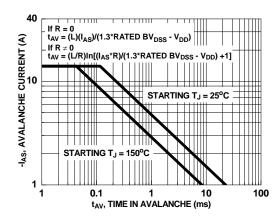


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to ON Semiconductor Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

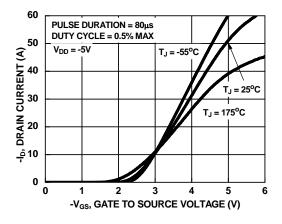


Figure 7. Transfer Characteristics

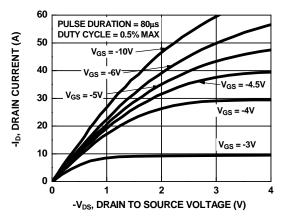


Figure 8. Saturation Characteristics

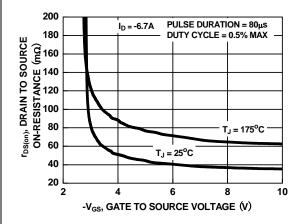


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

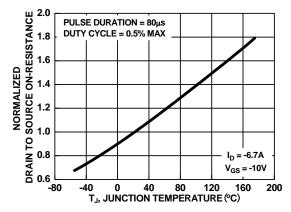


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

Typical Characteristics

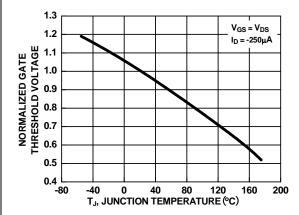


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

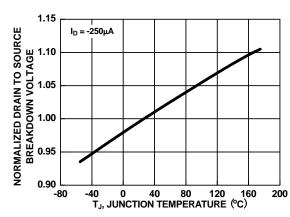


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

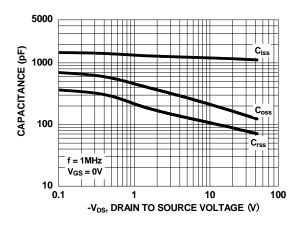


Figure 13. Capacitance vs Drain to Source Voltage

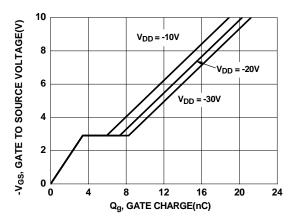


Figure 14. Gate Charge vs Gate to Source Voltage

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